



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE3AR2280CJZ		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001047472						
<b>Package</b>		PG-DIP-7-3		<b>Weight*</b>		645.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.632	0.72	0.72	7178	7178
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		6000	
wire	non noble metal	copper	7440-50-8	157.218	24.36	25.00	243643	250018
	noble metal	gold	7440-57-5	0.378	0.06	0.06	586	586
	encapsulation	organic material	carbon black	1333-86-4	2.344	0.36		3633
encapsulation	plastics	epoxy resin	-	63.288	9.81		98078	
	inorganic material	silicondioxide	60676-86-0	403.165	62.47	72.64	624791	726502
	leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10010
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2470	2470
glue	plastics	epoxy resin	-	0.365	0.06		566	
	noble metal	silver	7440-22-4	1.723	0.27	0.33	2670	3236
*deviation	< 10%				Sum in total:		100,00	1000000

### Important Remarks:

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